

Hindalco to Build iPhone Chassis Unit in Andhra

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New Delhi: Hindalco Industries is set to invest ₹586 crore to build an integrated aluminium extrusion facility, the primary raw material for manufacturing mobile phone chassis or enclosure, in Kuppam, Andhra Pradesh, for use in Apple's iPhone smartphones.

Hindalco's proposal will come up for approval of the State Investment Promotion Board (SIPB) on Thursday.

The move reflects Andhra Pradesh's aim to create an ecosystem for the iPhone in Kuppam, chief minister N Chandrababu Naidu's constituency, which falls in the tri-state area bordering Chennai and Bengaluru.

The new facility is expected to begin commercial production by March 2027 and generate 613 jobs in four years. The end product will be used for iPhone manufacturing, enabling Andhra Pradesh to catapult into the iPhone supply chain.

The project is significant as it is being set up in Kuppam, about 120 kilometres from Bengaluru, where Foxconn has started production of the iPhone 17 at a small scale in its second-largest manufacturing unit outside China.

Hindalco's project will be approved under the AP Electronics Component Manufacturing Policy 2025-30 and will be eligible for special incentives including subsidised land.

Andhra Pradesh has been trying to draw investments to Kuppam. "This is being done as it is not only the chief minister's constituency but also because it can tap into the infrastructure of both Bengaluru and Chennai," a senior official told ET. "In fact, Kuppam is closer to Bengaluru airport than Bengaluru city is to its own airport. Also, it is just 200 kms from Chennai. This tri-state area is perfect for investment projects as it can tap into the entire ecosystem."

Apart from Hindalco, SIPB is set to approve a ₹1,800-crore investment by Syrma SGS Technology for setting up India's largest multi-layer printed circuit board (PCB) and copper clad laminate (CCL) manufac-